Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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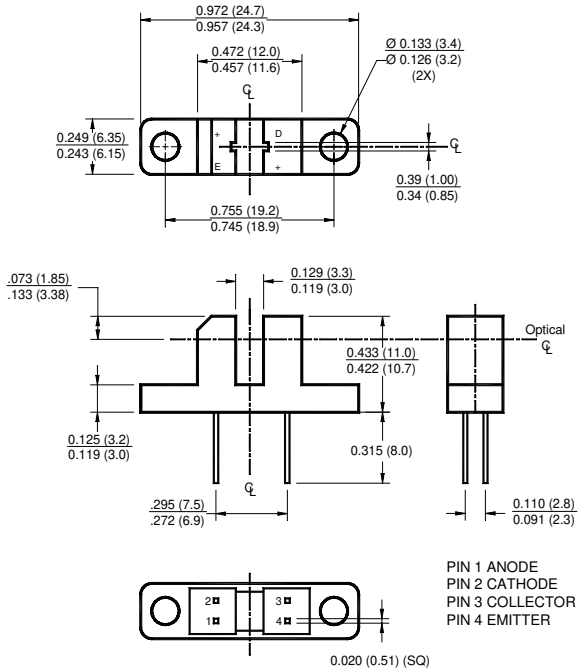
FAIRCHILD
SEMICONDUCTOR®

H21A1 / H21A2 / H21A3
PHOTOTRANSISTOR
OPTICAL INTERRUPTER SWITCH

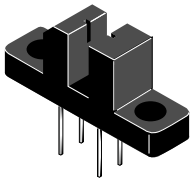
PACKAGE DIMENSIONS



NOTES:

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of ± .010 (.25) on all non-nominal dimensions unless otherwise specified.

DESCRIPTION

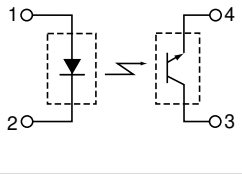


The H21A1, H21A2 and H21A3 consist of a gallium arsenide infrared emitting diode coupled with a silicon phototransistor in a plastic housing. The packaging system is designed to optimize the mechanical resolution, coupling efficiency, ambient light rejection, cost and reliability. The gap in the housing provides a means of interrupting the signal with an opaque material, switching the output from an "ON" to an "OFF" state.

FEATURES

- Opaque housing
- Low cost
- .035" apertures
- High $I_{C(ON)}$

SCHEMATIC



1. Derate power dissipation linearly 1.33 mW/°C above 25°C.
2. RMA flux is recommended.
3. Methanol or isopropyl alcohols are recommended as cleaning agents.
4. Soldering iron tip 1/16" (1.6mm) minimum from housing.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	T_{OPR}	-55 to +100	°C
Storage Temperature	T_{STG}	-55 to +100	°C
Soldering Temperature (Iron)(2,3 and 4)	T_{SOL-I}	240 for 5 sec	°C
Soldering Temperature (Flow)(2 and 3)	T_{SOL-F}	260 for 10 sec	°C
INPUT (EMITTER) Continuous Forward Current	I_F	50	mA
Reverse Voltage	V_R	6	V
Power Dissipation (1)	P_D	100	mW
OUTPUT (SENSOR) Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Collector Voltage	V_{ECO}	4.5	V
Collector Current	I_C	20	mA
Power Dissipation (T_C = 25°C)(1)	P_D	150	mW

ELECTRICAL / OPTICAL CHARACTERISTICS (T_A =25°C)(All measurements made under pulse condition)

PARAMETER	TEST CONDITIONS	SYMBOL	DEVICES	MIN	TYP	MAX	UNITS
INPUT (EMITTER) Forward Voltage	I_F = 60 mA	V_F	All	—	—	1.7	V
Reverse Breakdown Voltage	I_R = 10 µA	V_R	All	6.0	—	—	V
Reverse Leakage Current	V_R = 3 V	I_R	All	—	—	1.0	µA
OUTPUT (SENSOR) Emitter to Collector Breakdown	I_F = 100 µA, Ee = 0	BV_{ECO}	All	6.0	—	—	V
Collector to Emitter Breakdown	I_C = 1 mA, Ee = 0	BV_{CEO}	All	30	—	—	V
Collector to Emitter Leakage	V_{CE} = 25 V, Ee = 0	I_{CEO}	All	—	—	100	nA
COUPLED On-State Collector Current	I_F = 5 mA, V_{CE} = 5 V	$I_{C(ON)}$	H21A1	0.15	—	—	mA
			H21A2	0.30	—	—	
			H21A3	0.60	—	—	
	I_F = 20 mA, V_{CE} = 5 V		H21A1	1.0	—	—	
			H21A2	2.0	—	—	
			H21A3	4.0	—	—	
	I_F = 30 mA, V_{CE} = 5 V		H21A1	1.9	—	—	
			H21A2	3.0	—	—	
			H21A3	5.5	—	—	
Saturation Voltage	I_F = 20 mA, I_C = 1.8 mA	$V_{CE(SAT)}$	H21A2/3	—	—	0.40	V
	I_F = 30 mA, I_C = 1.8 mA		H21A1	—	—	0.40	V
Turn-On Time	I_F = 30 mA, V_{CC} = 5 V, R_L = 2.5 KΩ	t_{on}	All	—	8	—	µs
Turn-Off Time	I_F = 30 mA, V_{CC} = 5 V, R_L = 2.5 KΩ	t_{off}	All	—	50	—	µs

Figure 1. Output Current vs. Input Current

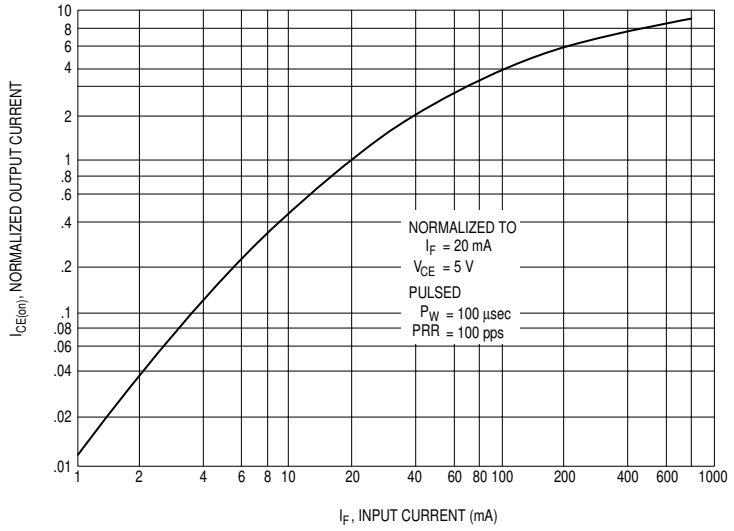


Figure 2. Output Current vs. Temperature

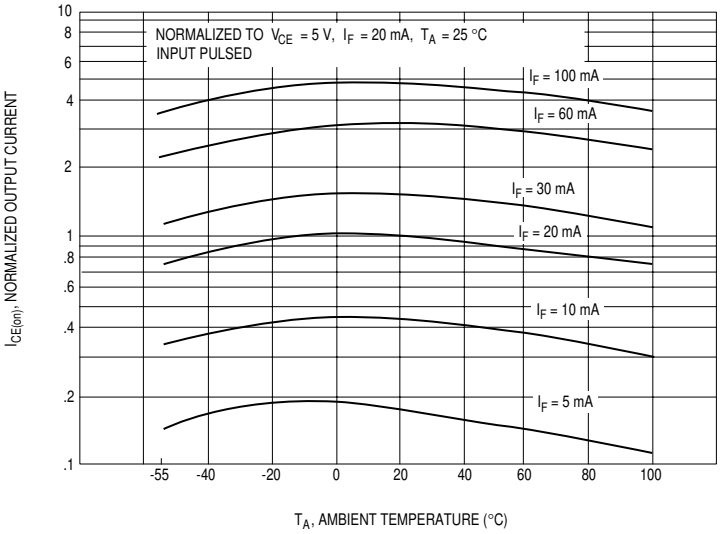


Figure 3. $V_{CE(SAT)}$ vs. Temperature

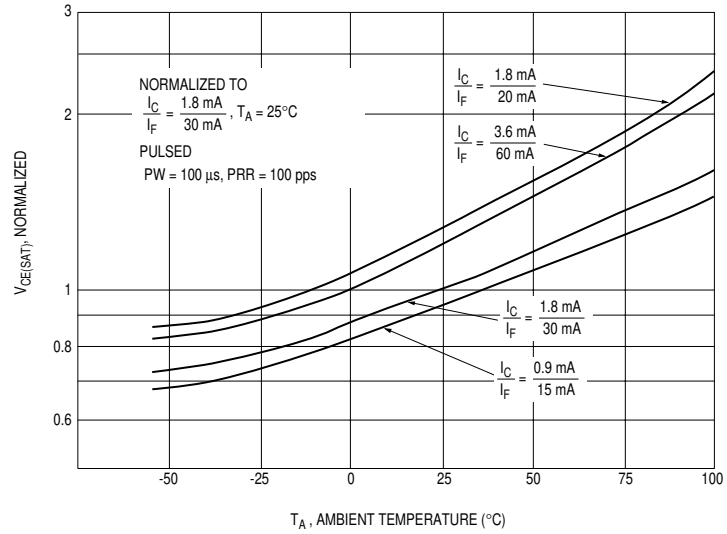


Figure 4. Leakage Current vs. Temperature

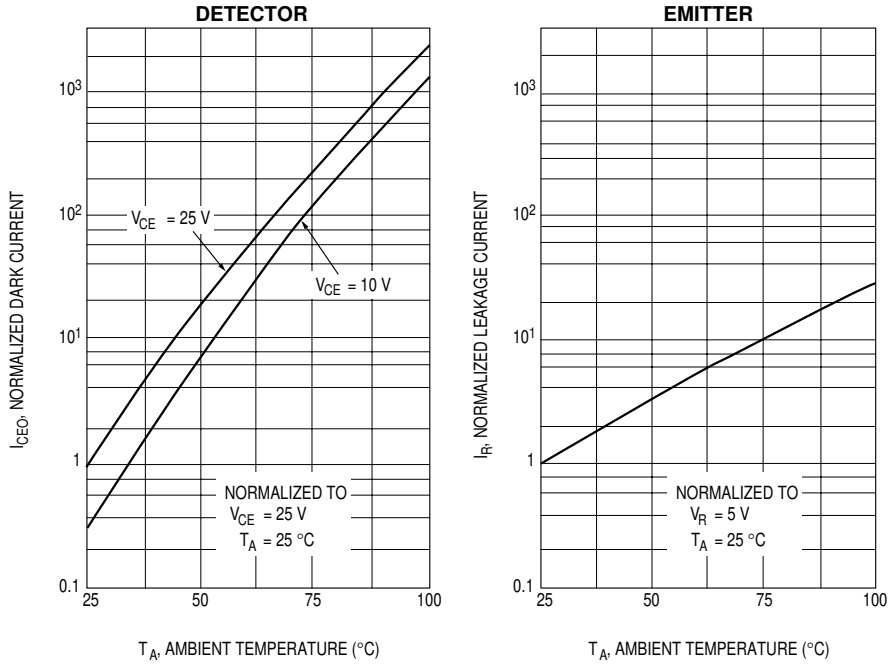


Figure 5. Switching Speed vs. RL

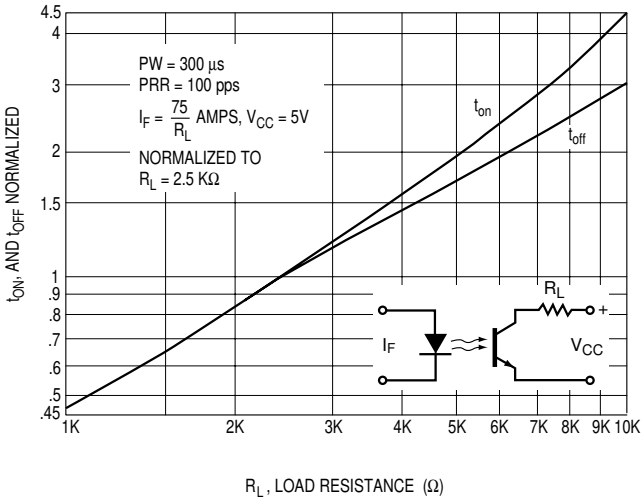
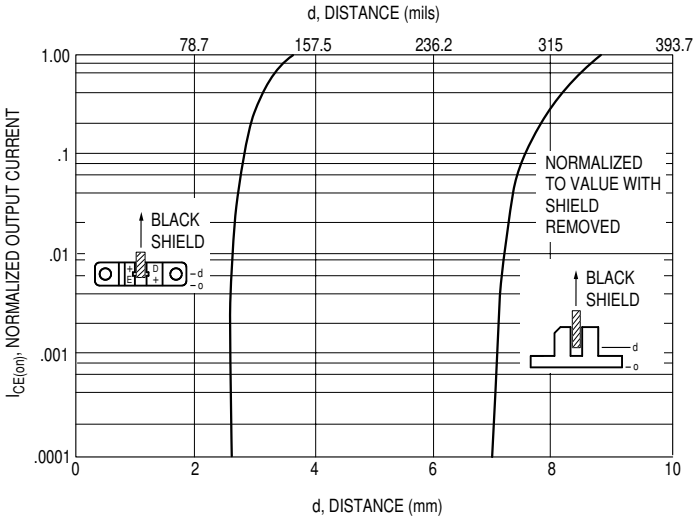


Figure 6. Output Current vs. Distance



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